eps

ESS 300 / ESS 500

Selective Soldering Machine

System Features

Precise, accurate, reliable soldering of through-hole components in mixed boards with previously soldered SMT components

Reduce board processing time as compared with hand soldering

Reduce direct labor costs, decrease rework costs, increase consistency over hand soldering through-hole components

One, all inclusive system - Flux, Preheat, and Solder

Touch screen interface for easy on instrument setup, programming and parameter control
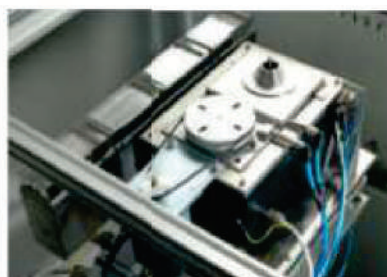
Instrument programming flexibility and control over preheat, temperature, soldering dwell times, location, direction, and more...

Off-line programming with photo scan and Gerber import software for convenient machine setup

Variety of Nozzles available for flexibility - Wettable and Specility Nozzles*

Lead-free compatible

Specifications	ESS - 300	ESS - 500
Max. PCB Size	310 x 310 mm (12" x 12")	500 x 500 mm (19.7" x 19.7")
Max. Clearance on Solder Side*	25 mm (1")	25 mm (1")*
Position accuracy above fluxer, preheater and solder nozzle	±0.1 mm (±0.004")	±0.1 mm (±0.004")
Precision Spray Fluxer Module		
Flux Tank	2L Stainless Steel	2L Stainless Steel
Flux Speed Max.	6 m / min	6 m / min
Preheat	900 W IR Heaters	1200 W IR Heaters
Solder Module		
Nozzles	Wettable, Special	Wettable, Special
Smallest Nozzle Diameter	4.0 mm	4.0 mm
Solder Capacity	400°C (725°F)	400°C (725°F)
Warm-up Time	Approx. 45 minutes	Approx. 45 minutes
Air Pressure	5.5 bar (80psi)	5.5 bar (80psi)
Power	230/400V, 50/60 Hz 1/3 phase	230/400V, 50/60 Hz 1/3 phase
Max. Power Consumption	2.5 kW	3.0 kW
Exhaust Power (Supplied by customer)	150 m³ / hour, 100 mm(4") dia	150 m³ / hour, 100 mm(4") dia
Length	1240 mm (48.8")	1440 mm (56.7")
Width	1050 mm (41.3")	1250 mm (49.2")
Height	1600 mm (63")	1600 mm (63")

Specifications are subject to change without notice